SHARP PC8110xNSZ Series

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Photocoupler with Built-in Schottky Barrier Diode

■ Features

- 1. High speed response at turn-off time due to built-in schottky barrier diode
- 2. 4-pin DIP package
- 3. Isolation voltage (Viso: 5kV_{rms})

■ Applications

- 1. Refrigerators
- 2. Air conditioners
- 3. Various home appliances

■ Rank Table

Model No.	Rank mark	Ic (mA)	Conditions
PC81100NSZ	A, B, C or no mark	2.5 to 20	
PC81101NSZ	A	3.0 to 6.0	
PC81102NSZ	В	5.0 to 10	I _F =5mA
PC81103NSZ	C	7.5 to 15	Vce=5V
PC81105NSZ	A or B	3.0 to 10	Ta=25°C
PC81106NSZ	B or C	5.0 to 15	
PC81108NSZ	A, B or C	3.0 to 15	

■ Absolute Maximum Ratings

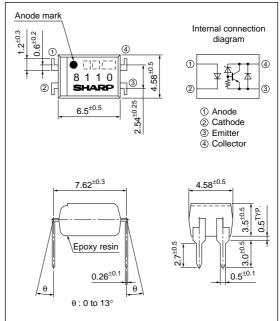
(Ta=25°C))
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= Absolute maximum rutings (1a=25 C					
	Parameter	Symbol	Rating	Unit	
Input	Forward current	I_F	50	mA	
	*1 Peak forward current	IFM	1.0	A	
	Reverse voltage	V_{R}	6	V	
	Power dissipation	P	70	mW	
Output	Collector-emitter voltage	Vceo	70	V	
	Emitter-collector voltage	VECO	0.1	V	
	Collector current	Ic	30	mA	
	Collector power dissipation	Pc	150	mW	
	Total power dissipation	\mathbf{P}_{tot}	200	mW	
Operating temperature		Topr	-30 to +100	°C	
	Storage temperature	Tstg	-55 to +125	°C	
	*2 Isolation voltage	$V_{\rm iso}$	5	kVrms	
	*3 Soldering temperature	Tsol	260	°C	

^{*1} Pulse width<=100µs, Duty ratio=0.001 *2 40 to 60%RH, AC for 1 minute, f=60Hz

■ Outline Dimensions

(Unit: mm)



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Internet address for Electronic Components Group http://www.sharp.co.jp/ecg/

^{*2 40} to 60% RH, A *3 For 10 seconds

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	Ele	ctro-optic	al Char	acteristi	cs				(Ta=25°C)
	Parameter S			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	F	Forward voltage		V_F	I _F =20mA	_	1.2	1.4	V
	P	Peak forward voltage		V _{FM}	I _{FM} =0.5A	_	_	3.0	V
	Reverse current		IR	V _R =4V	_	_	10	μΑ	
	Т	Terminal capacitance		Ct	V=0, f=1kHz	_	30	250	pF
Output	C	Collector dark current		Iceo	Vce=50V, I _F =0	_	_	100	nA
Out	*4C	*4 Collector-emitter breakdown voltage		BVCEO	Ic=0.1mA, I _F =0	70	_	-	V
stics	C	Collector current		Ic	I _F =5mA, V _{CE} =5V	2.5	_	20	mA
	Collector-emitter saturation voltage		V _{CE} (sat)	I=20mA, Ic=1mA	_	0.15	0.35	V	
	Is	Isolation resistance		Riso	DC500V, 40 to 60%RH	5×10 ¹⁰	1×10 ¹¹	-	Ω
	Floating capacitance		Cf	V=0, f=1MHz	_	0.6	1.0	pF	
teri		Not saturated	Rise time	tr	Vce=2V, Ic=2mA, Rl=100Ω	_	3	20	
ırac			Fall time	tf		_	2	10	
Transfer characteristics	me	Turn-on time	ton		_	2	13]	
	se ti	g Saturated 1	Storage time	ts	$V_{CC}=5V$, $I_F=20mA$, $R_L=10k\Omega$	_	9	50]
	auoc.	Turn-off time	toff		_	23	90	μs	
	Saturated 1	Turn-on time	ton		_	3	13	1	
	-	Saturated 2	Storage time	ts	$V_{CC}=5V$, $I_F=20mA$, $R_L=100k\Omega$	-	10	50	
			Turn-off time	toff		_	27	100	1

^{*4} It has negative resistance characteristics due to built-in base-emitter resistance. Please be careful not to apply voltage that exceed absolute maximum rating.

Fig.1 Forward Current vs. Ambient Temperature

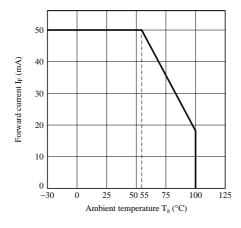


Fig.2 Diode Power Dissipation vs. Ambient Temperature

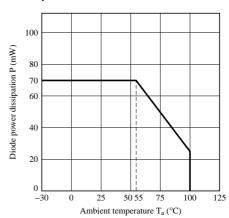


Fig.3 Collector Power Dissipation vs. Ambient Temperature

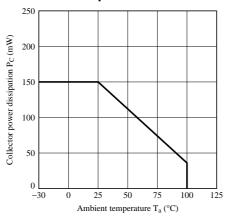


Fig.5 Peak Forward Current vs. Duty Ratio

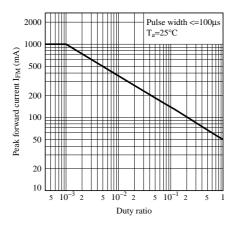


Fig.7 Current Transfer Ratio vs. Forward Current

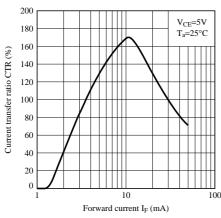


Fig.4 Total Power Dissipation vs. Ambient Temperature

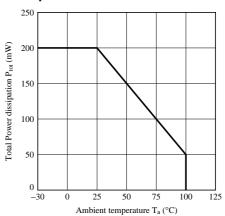


Fig.6 Forward Current vs. Forward Voltage

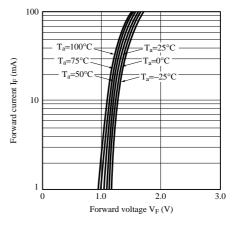


Fig.8 Collector Current vs. Collector-emitter Voltage

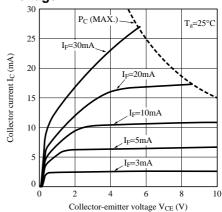


Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature

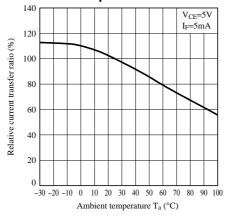


Fig.11 Collector Dark Current vs. Ambient Temperature

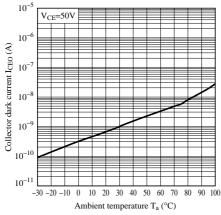


Fig.13 Response Time vs. Load Resistance (not saturated made)

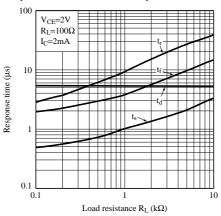


Fig.10 Collector - emitter Saturation Voltage vs. Ambient Temperature

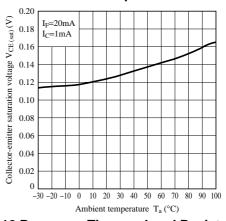


Fig.12 Response Time vs. Load Resistance (saturated mode)

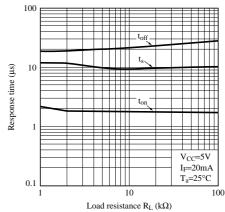


Fig.14 Voltage gain vs Frequency

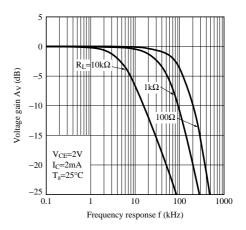


Fig.15 Collector-emitter Saturation Voltage vs. Forward Current

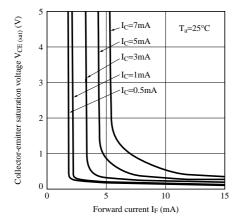
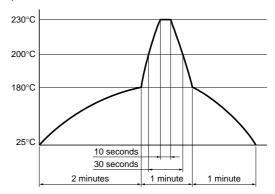


Fig.16 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.



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- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.
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